TITLE: SPECIFICATION CONTROL DRAWING

PART IDENTIFIER: SMT3725TALNF

DESCRIPTION: SURFACE MOUNT TERMINATION, TUNED FOR TELECOM BANDS, LEAD FREE

ASSEMBLY DWG: 1102034

1.0 SPECIFICATIONS:

- 1.1 ELECTRICAL:
 - 1.1.1 IMPEDANCE: 50Ω NOMINAL.
 - 1.1.2 FREQUENCY: 800 MHZ 2700 MHZ.
 - 1.1.3 VSWR: 1.15:1 MAX.
 - 1.1.4 INPUT POWER:
 - 1.1.4.1 100 WATTS. CHIP SOLDERED TO MOUNTING SURFACE. MOUNTING SURFACE TEMPERATURE MAINTAINED AT 100 °C MAXIMUM. APPLY LINEAR DE-RATING OF INPUT POWER TO 0 WATTS AT 150 °C.
- 1.2 MECHANICAL:
 - 1.2.1 OUTLINE DWG: SEE SHEET 2.
 - 1.2.2 WORKMANSHIP: PER MIL-PRF-55342
 - 1.2.3 THERMAL IMPEDANCE (R_☉)
 - 1.2.3.1 0.625 °C / WATT R_{\odot} FROM RESIST FILM TO MOUNTING SURFACE DIRECTLY UNDER CENTER OF CHIP. CHIP SOLDERED DIRECTLY TO MOUNTING SURFACE.
 - 1.2.4 FILM TEMPERATURE (T_F)
 - 1.2.4.1 200 °C ABSOLUTE MAXIMUM FILM TEMPERATURE. DE-RATE TO 150 °C MAXIMUM FILM TEMPERATURE FOR ALL MILITARY/HIGH-RELIABILITY APPLICATIONS.
 - 1.2.5 THERMAL
 - 1.2.5.1 DETERMINE MAXIMUM MOUNTING SURFACE TEMPERATURE BY APPLYING THE FOLLOWING FORMULA: $T_S = T_F (P_{MAX} \times R_{\odot})$

WHERE: T_S = MAXIMUM MOUNTING SURFACE TEMPERATURE T_F = MAXIMUM FILM TEMPERATURE P_{MAX} = MAXIMUM APPLIED INPUT POWER R_{Θ} = CHIP THERMAL IMPEDANCE.

- 1.3 ENVIRONMENTAL:
 - 1.3.1 TEMPERATURE RANGE:
 - 1.3.1.1 NON-OPERATING: -55°C TO +150°C. 1.3.1.2 OPERATING: -55°C TO +150°C.
- 2.0 UNIT MARKING: NONE.
- 3.0 QUALITY ASSURANCE:
 - 3.1 SAMPLE INSPECT PER ANSI/ASQC Z1.4 GENERAL INSPECTION, LEVEL II, AQL = 1.0.
 - 3.1.1 VISUAL AND MECHANICAL PER 824W154.
 - 3.1.2 DC RESISTANCE: $45.6\Omega \pm 5\%$.
 - 3.2 DATA REQUIREMENTS:
 - 3.2.1 NO TEST DATA REQUIRED FOR CUSTOMER.
 - 3.2.2 DATA RETENTION 24 MONTHS.
- 4.0 PACKAGING: STANDARD PACK PER 755W002.

EMC TECHNOLOGY	CAGE CODE # 24602		DWG#	1010655000		
8851 SW OLD KANSAS AVE.	CHANGE NOTICE	PRELIMINARY	REV LVL	С		
STUART, FL 34997			SHEET	1	OF	2

